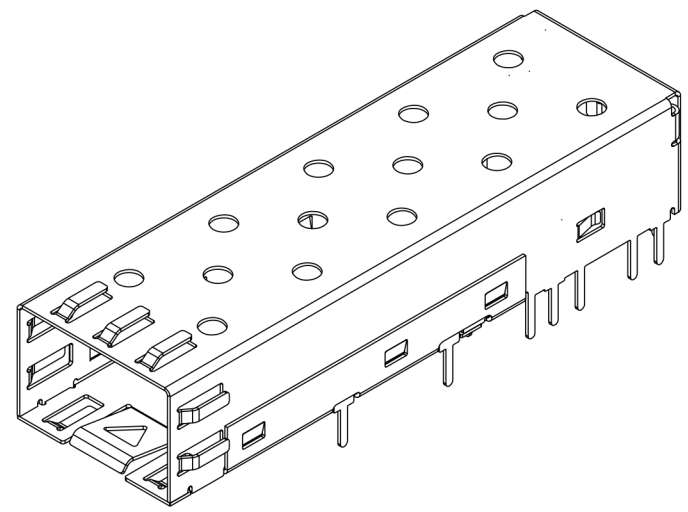
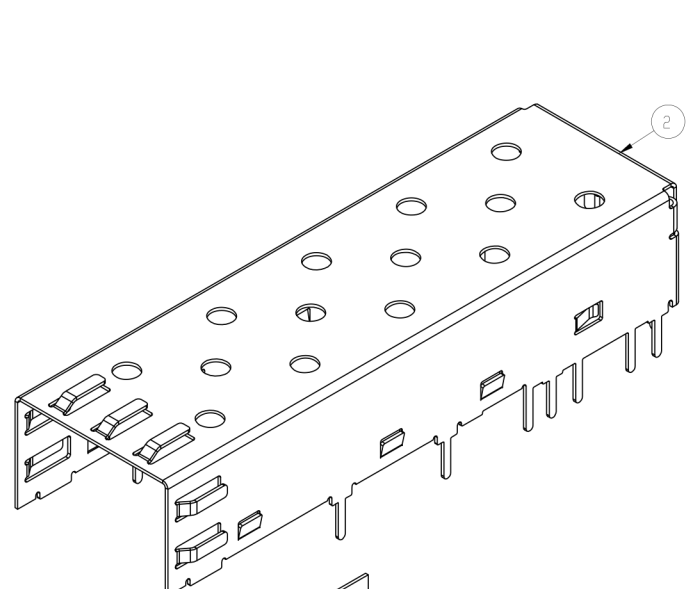


CATEGORY	DESCRIPTION	P/N #
CONNECTOR	SFP 1X1 直角	SFP-001-A

REV.	ECN NO	DESCRIPTION	REVISED	DATE
A1	———	新訂圖面	WZ	2009.08.10



PART NUMBER	DESCRIPTION

NOTES:
 1. MATERIAL: PHOSPHOR BRONZE C51910, (SEE COMPONENTS FOR DETAILS)
 PLATING FINISH 1: 2.54-3.81 μm (100-150 U²) BRIGHT TIN MIN. (WHISKER CONTROLLED REQ'D) OVER 1.27 μm (50 U²) MIN.
 HIGH TEMP NICKEL UNDER PLATING OVER COPPER FLASH.
 RACK PLATING MAY BE REQUIRED.(BRIGHT TIN IS FOR WAVE SOLDER)
 PLATING FINISH 2 :2.54-3.81 μm (100-150 U²) MATTE TIN MIN. (WHISKER CONTROLLED REQ'D) OVER 1.27 μm (50 U²) MIN.
 HIGH TEMP NICKEL UNDER PLATING OVER COPPER FLASH.
 RACK PLATING MAY BE REQUIRED.(MATTE TIN IS FOR SMT REFLOW INCL DING THE TEMPERATURE REFLOW REQUIREMENT * MIN. FOR 7MIN.SECONDS.) SEE PART NUMBER FOR PLATING OPTIONS.

2	SEE TABLE 1	TOP CAGE	
1	SEE TABLE 1	BOTTOM CAGE	
ITEM No.	PART NUMBER	QTY	DESCRIPTION

TABLE 1

CAGE P/N	ITEM 1 P/N (BOTTOM CAGE)	ITEM 2 P/N (TOP CAGE)		
U77-A1112-100U77-1110-3002U77-1110-4002U77A1112	100	BRIGHT TIN	SEE NOTE1, PLATING FINISH 11.2 mm	SOLDER PIN HEIGHT
U77-A1113-100U77-1110-3003U77-1110-4003U77A1113	100	BRIGHT TIN	SEE NOTE1, PLATING FINISH 13.2 mm	SOLDER PIN HEIGHT
U77-A1114-100U77-1110-3004U77-1110-4004U77A1114	100	BRIGHT TIN	SEE NOTE1, PLATING FINISH 11.8 mm	SOLDER PIN HEIGHT
U77-A1112-300U77-1110-3002U77-1110-4002U77A1112	300	MATTE TIN	SEE NOTE1, PLATING FINISH 21.2 mm	SOLDER PIN HEIGHT
U77-A1113-300U77-1110-3003U77-1110-4003U77A1113	300	MATTE TIN	SEE NOTE1, PLATING FINISH 23.2 mm	SOLDER PIN HEIGHT
U77-A1114-300U77-1110-3004U77-1110-4004U77A1114	300	MATTE TIN	SEE NOTE1, PLATING FINISH 21.8 mm	SOLDER PIN HEIGHT

UNLESS OTHERWISE SPECIFIED TOLERANCES	SCALE: 1/1	UNIT: mm	DWG. NO: WI-061-234
	SIZE: A3	PAGE: 1 OF 2	
DECIMALS: X :±0.5 X.X :±0.3 X.XX :±0.2	ANGLES: X :±1° X.X :±0.5°	APPROVED BY	CHECKED BY
		DICK	WZ
CUSTOMER COPY			

